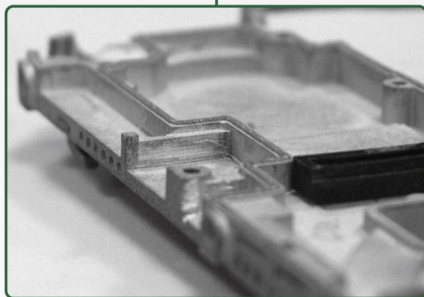


# Industrial/ Military Notebook PC



## Thermal Management + EMI Shielding

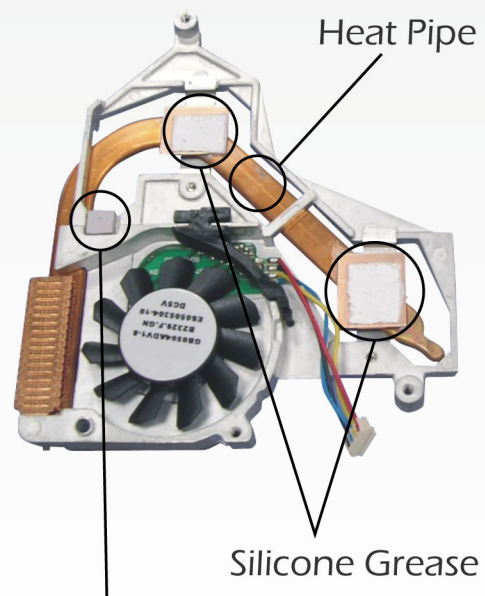


▲ EMI/Water Seal FIPEG



▲ Mold-In-Place (MIPG) For CF/PCMCIA Card

▼ Thermal Module



Gap Fillers

TennVac Taiwan

Tel: +886 2 2695-1213

Email: mtseng@tennvac.com

Website: www.tennvac.com

TennVac China

Tel: +86 755-2695-1701

Email: tliu@tennvac.com

Website: www.tennvac.com

TennMax America

Tel: +1 360-546-3824

Email: jeff@tennmaxusa.com

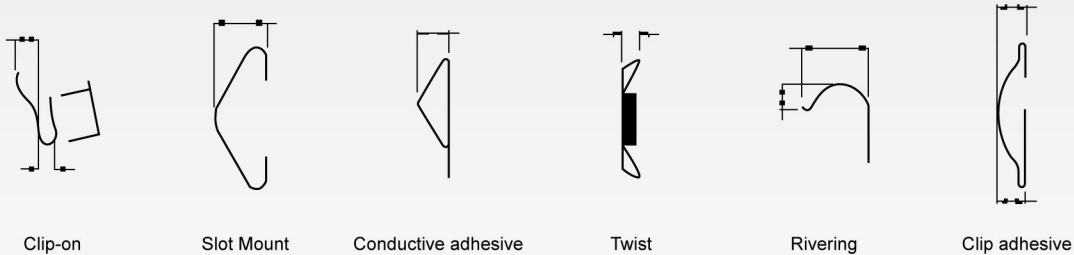
Website: www.tennmaxusa.com

▼ Thermal pad

| Thermal gap filler                    | T-pad-2000 | T-Pad-3000 | T-Pad-5000  | T-Pad-7000 |
|---------------------------------------|------------|------------|-------------|------------|
| <b>Construction &amp; Composition</b> | Silicone   | Silicone   | Silicone    | Silicone   |
| <b>Filler</b>                         | Ceramic    | Ceramic    | Ceramic     | Ceramic    |
| <b>Color</b>                          | Blue       | Gray       | Blue-Violet | Gray       |
| <b>Density (g/cc)</b>                 | 2.60       | 2.8        | 3.26        | 2.7        |
| <b>UL Rating</b>                      | UL 94      | UL 94      | UL 94       | UL 94      |
| <b>Continuous Use Temp (°C)</b>       | -40 ~ 200  | -40 ~ 200  | -40 ~ 200   | -40 ~ 200  |
| <b>Thermal Conductivity (W/mk)</b>    | 1.2        | 2.0        | 3.0         | 5.0        |

▼ Finger stock

Finger strips made from beryllium copper can be used for closing a gap between two surfaces and provide the high EMI shielding effectiveness. We offer Clip-on, Slot mount, Conductive adhesive, Twist, Riveting, Clip adhesive and other mounting solution.



▼ Foam Gasket

Foam gasket is a lightweight, flexible and low cost EMI solution for most popular electronic devices. We offers over 250 different profiles to meet all of your shielding needs, rectangular, T-shape, D-shape, L-shape, P-shape, U-shape, and more.

